

HSEC8-149-01-L-DV-A



HSEC8-DV SERIES

(0.80 mm) .0315"

VERTICAL EDGE RATE® CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com/HSEC8-DV

Insulator Material:

Black Liquid Crystal Polymer

Contact:

BeCu

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Current Rating:

2.8 A per pin

(2 adjacent pins powered)

Operating Temp:

-55 °C to +125 °C

RoHS Compliant:

Yes

Card Mates:

(1.60 mm) .062" card,
(2.36 mm) .093" card,
HSC8

Cable Mates:

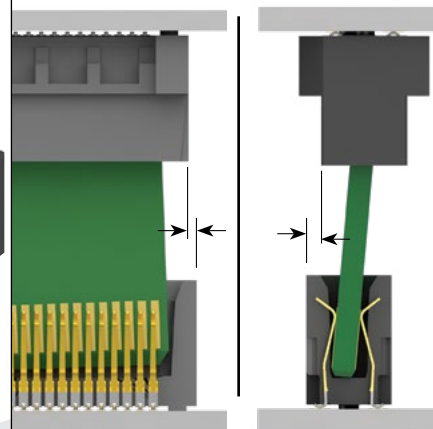
ECDP



Mates with (1.60 mm) .062"
or (2.36 mm) .093" cards



MISALIGNMENT MITIGATION



Custom designs compensate for misalignment.

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (10-60)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

HIGH-SPEED CHANNEL PERFORMANCE

HSEC8-DV

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

28
Gbps

HSEC8

1 POSITIONS PER ROW

CARD THICKNESS

PLATING OPTION

DV

A

OTHER OPTION

09, 10, 13, 20,
25, 30, 37, 40, 49,
50, 60, 70, 80, 100
(13, 25, 49 only available
with -L or -L2 option;
09 only available with -L2 option;
37 only available with -L option)

-01
= (1.60 mm) .062"
thick card

-03
= (2.36 mm) .093"
thick card

-L
= 10 μ" (0.25 μm)
Gold on contact,
Matte Tin on tail

-S
= 30 μ" (0.76 μm)
Gold on contact,
Matte Tin on tail

-K
= (7.01 mm) .276" DIA Polyimide Film
Pick & Place Pad; with -01 card,
= (6.25 mm) .246" DIA Polyimide Film
Pick & Place Pad; with -03 card

-BL
= Board Locks -01 card only
(Weld tab standard)

-L
= Latching Option; -01 card only
(13, 25, 37, 49 only)
(Weld tab standard)

-L2
= ECDP Latching; -01 card only
(09, 13, 25, 49 only)
(For use with ECDP)
(Weld tab standard)

-WT
= Weld tab

-TR
= Tape & Reel
(09 - 70 only)

-FR
= Full Reel Tape & Reel Packaging
(Must order max. quantities per reel.
Contact Samtec for parts per reel)
(09 - 70 only)

CABLE	CONNECTOR
ECDP-04	HSEC8-109-L2
ECDP-08	HSEC8-113-L2
ECDP-16	HSEC8-125-L2
ECDP-32	HSEC8-149-L2

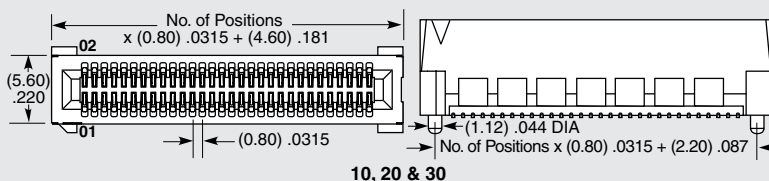
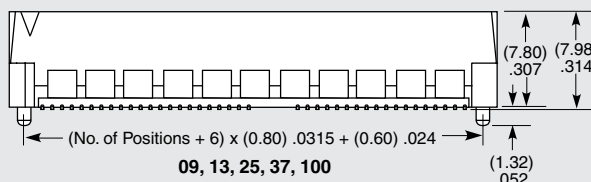
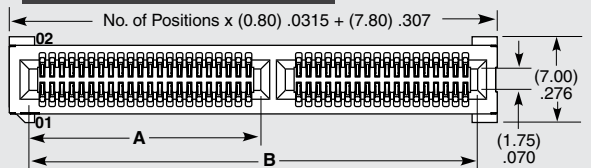
POSITIONS PER ROW	A	B
09†	(4.50) .177	(11.80) .465
13†	(6.10) .240	(15.00) .591
25†	(6.10) .240	(24.60) .969
37†	(18.10) .713	(34.20) 1.346
40	(18.90) .744	(36.60) 1.441
49†	(22.90) .902	(43.80) 1.724
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071
70†	(26.90) 1.059	(60.60) 2.386
80†	(26.90) 1.059	(68.60) 2.701
100†	(26.90) 1.059	(84.60) 3.331

Positions where no dimensions are given do not have keying feature.
* Mates with ECDP Series.
† Available with -01 Card Only.

Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

Some lengths, styles and options are non-standard, non-returnable.



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.